REMARKS

Claims 1-17 are pending in the application.

Claims 7-11 and 13-17 have been previously withdrawn.

Claims 1-6 and 12 have been rejected.

Claim 1 has been amended as set forth herein.

Claims 1-6 and 12 remain pending in this application.

Reconsideration of the claims is respectfully requested.

I. CLAIM REJECTIONS UNDER 35 U.S.C. § 112

Claims 1-6 and 12 were rejected under 35 U.S.C. § 112, second paragraph as being indefinite for failing to particularly point out and distinctly claim the subject matter. The Applicant has amended Claim 1 as shown above. In light of these amendments, the 112 rejection is believed to be obviated, and is traversed.

For the convenience of the Examiner, a "clean" copy of amended claim 1 is on the following page:

1. (Currently Amended) A process for fabricating an integrated electronic circuit, said

integrated circuit having

a substrate,

an intermediate layer of permeable material,

an interconnect layer comprising initially a part of a sacrificial material and extending

beneath the intermediate layer, and

interconnect elements formed within a subpart of said part of sacrificial material of the

interconnect layer,

the process comprising: forming at least one air gap within the interconnect layer by

removing, through the intermediate layer, at least said subpart of sacrificial material of the

interconnect layer by bringing the permeable material into contact with an agent for removing

the sacrificial material, to which agent the permeable material is resistant, said intermediate layer

remaining rigidly linked to the substrate outside said defined portion;

whereby the at least one air gap is formed above only a defined portion of a surface of a

substrate, and said defined portion being smaller than the surface of the substrate.

Examination on the merits is respectfully requested.

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CONCLUSION

As a result of the foregoing, the Applicant asserts that the remaining Claims in the

Application are in condition for allowance, and respectfully requests an early allowance of such

Claims.

If any issues arise, or if the Examiner has any suggestions for expediting allowance of

this Application, the Applicant respectfully invites the Examiner to contact the undersigned at

the telephone number indicated below or at wmunck@munckbutrus.com.

The Commissioner is hereby authorized to charge any additional fees connected with this

communication or credit any overpayment to Deposit Account No. 50-0208.

Respectfully submitted,

MUNCK BUTRUS P.C.

Date: Hug 3, 2006

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